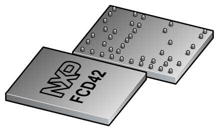


SOT2156-1

FCD42, flip chip die, 42 terminals; 2.1 mm x 1.7 mm x 0.225 mm body

8 September 2021 **Package information**

1 Package summary

Package type descriptive code	FCD42
Package type industry code	FCD42
Package style descriptive code	FCD (flip chip die)
Mounting method type	S (surface mount)
Issue date	06-08-2021
Manufacturer package code	98ASA01817D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.07	2.1	2.13	mm
package width	1.67	1.7	1.73	mm
package height	-	0.225	0.25	mm
actual quantity of termination	-	42	-	

2 Package outline

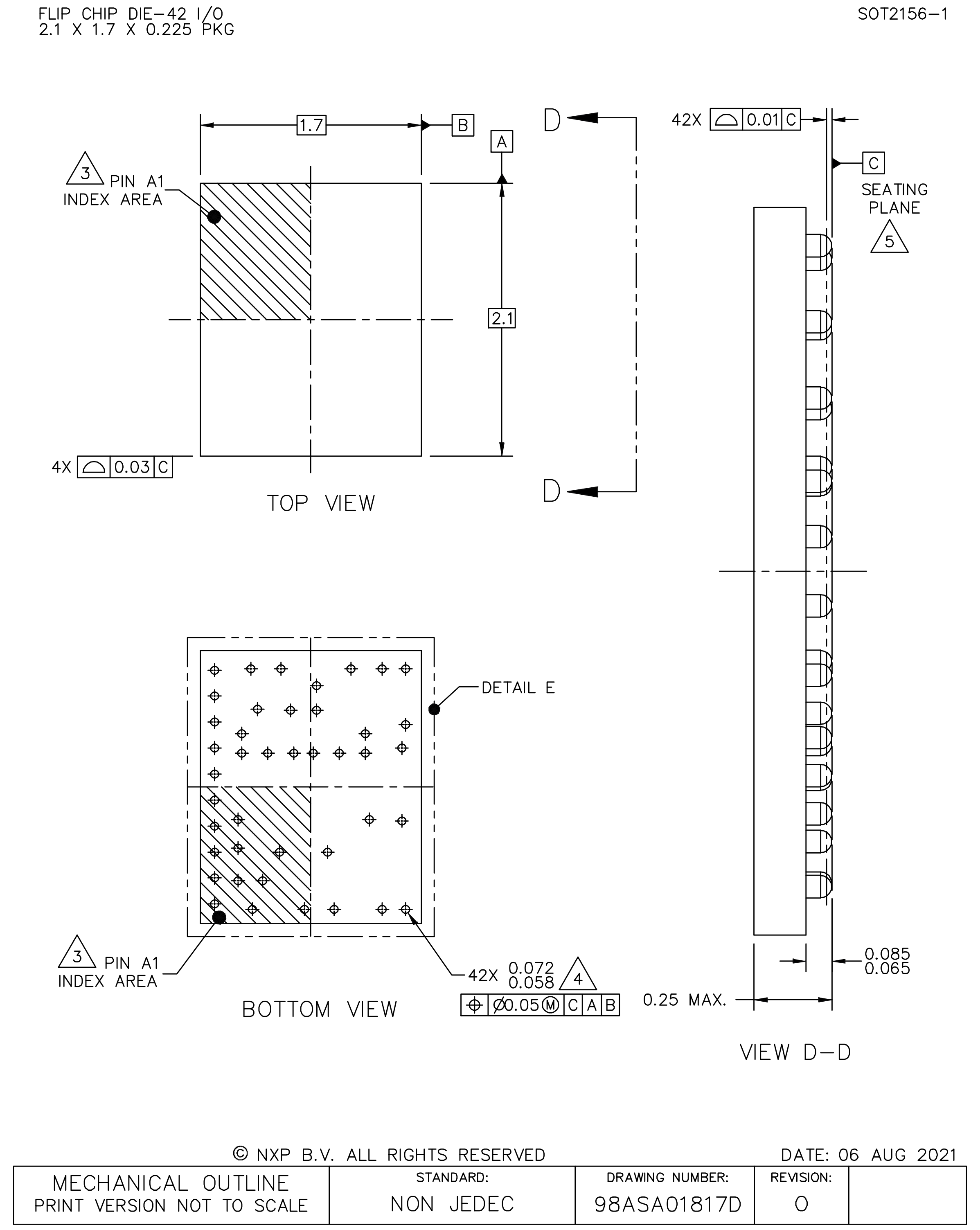
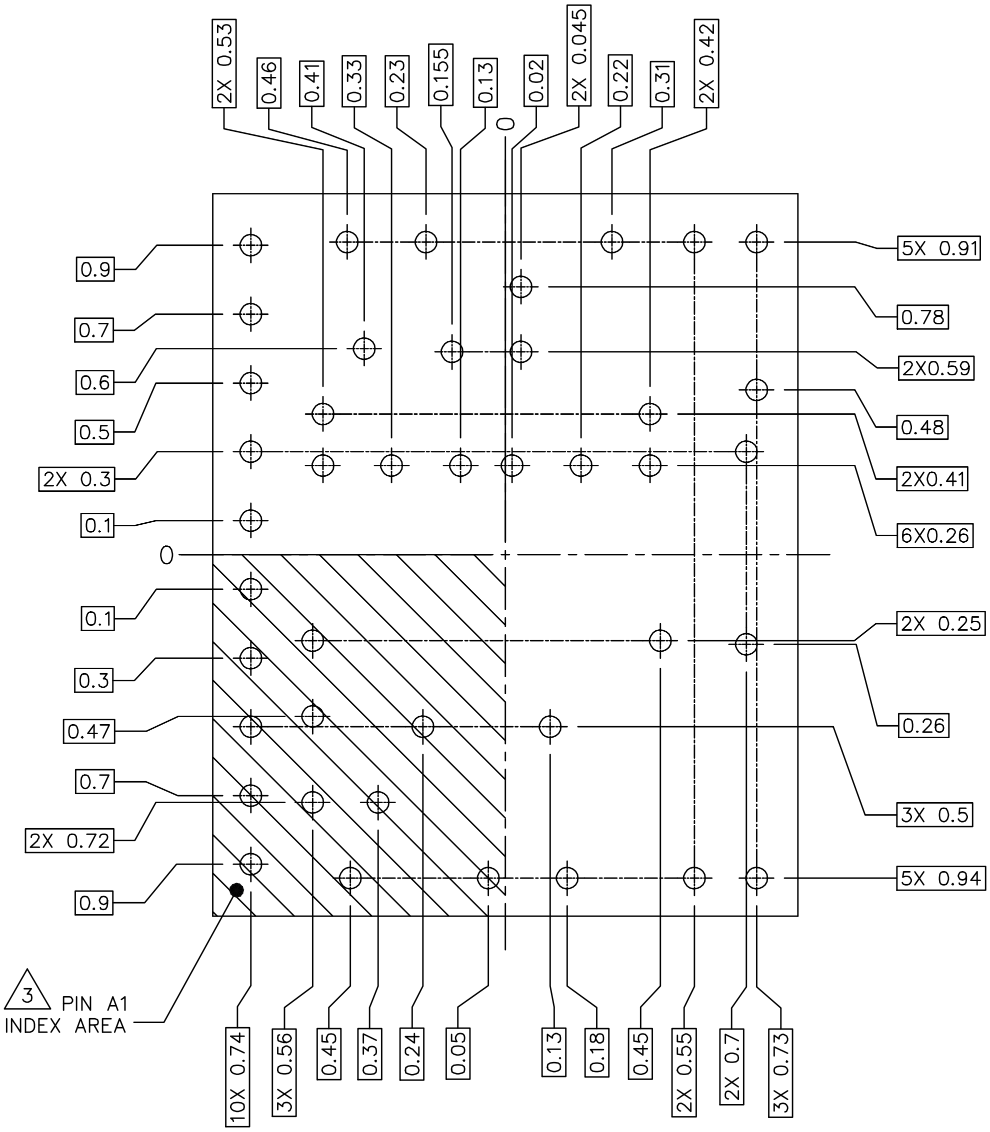


Figure 1. Package outline FCD42 (SOT2156-1)

FLIP CHIP DIE–42 I/O
2.1 X 1.7 X 0.225 PKG

SOT2156–1



DETAIL E

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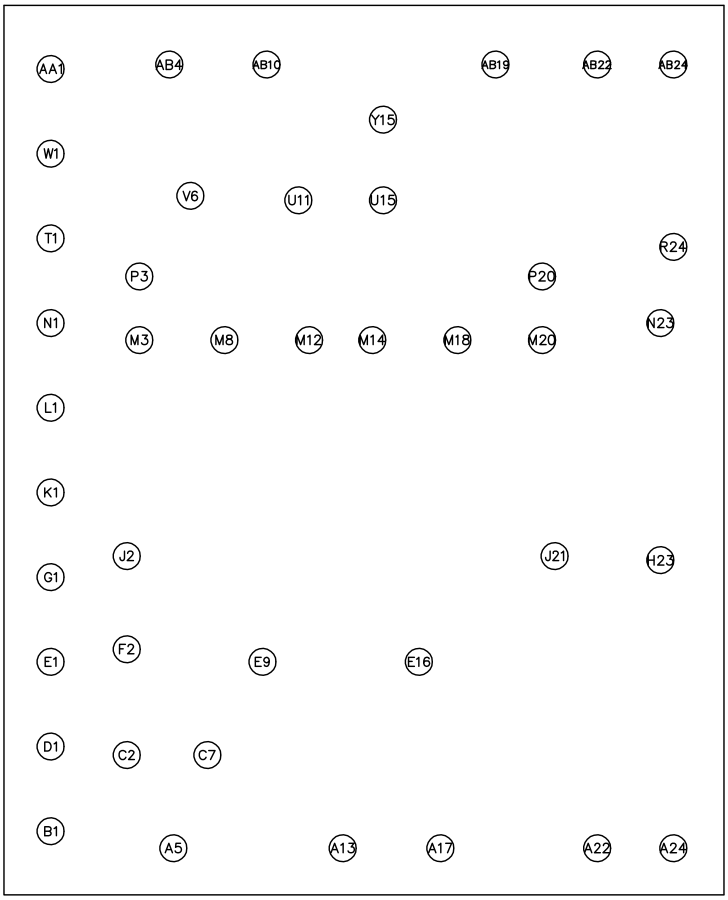
DATE: 06 AUG 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01817D	REVISION: 0	

Figure 2. Package outline detail of FCD42 (SOT2156-1)

FLIP CHIP DIE–42 I/O
2.1 X 1.7 X 0.225 PKG

SOT2156–1



PIN NUMBERS
(VIEWED FROM BOTTOM, SAME AS DETAIL E)

DATE: 06 AUG 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01817D	REVISION: O	

Figure 3. Package outline detail of FCD42 (SOT2156-1)

FLIP CHIP DIE–42 I/O
2.1 X 1.7 X 0.225 PKG

SOT2156–1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DATE: 06 AUG 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01817D	REVISION: O	

Figure 4. Package outline note FCD42 (SOT2156-1)

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